



# Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Pavilion Wave Desktop PC 600 (ENERGY STAR)

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm MB, Memory, HDD PCA,	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Adapter	2
External electrical cables and cords	Power cord	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 crisscross screw driver	2#
Description #2 hexagon screw driver	T15
Description #3 electric iron	QUICK 310
Description #4	
Description #5	

## 3.0 Product Disassembly Process

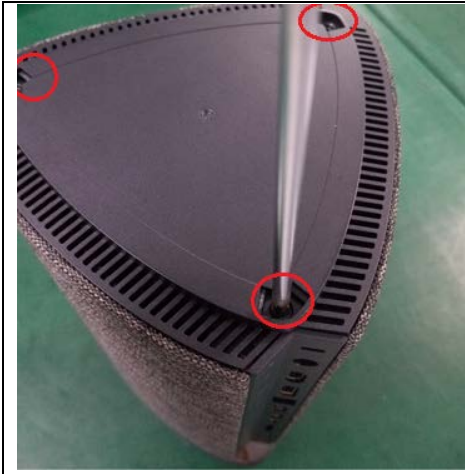
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove 3pcs of foot rubbers to bottom cover
2. Remove 3pcs screws from bottom cover, remove bottom cover from chassis.
3. Remove Chassis outer covering.
4. Remove Rear I/O bezel.
5. Remove all cable from the unit.
6. Remove HDD from the unit.
7. Remove Screw that connect Chassis and top cover..
8. Remove top bezel and top cover from units.
9. Remove Memory cover.
10. Remove screws from chassis iron part.
11. Separate chassis iron part.
12. Remove Memory from Motherboard.
13. Remove heat sink from Motherboard.
14. Remove Motherboard from chassis Iron part.
15. Remove system fan and speaker from chassis iron part.
16. Open the power adapter by mechanical force and remove PCA and capacitor > 25mm in size..

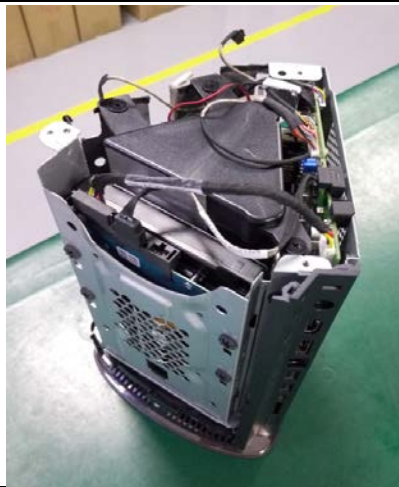
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



1. Remove 3pcs of foot rubbers to bottom cover.



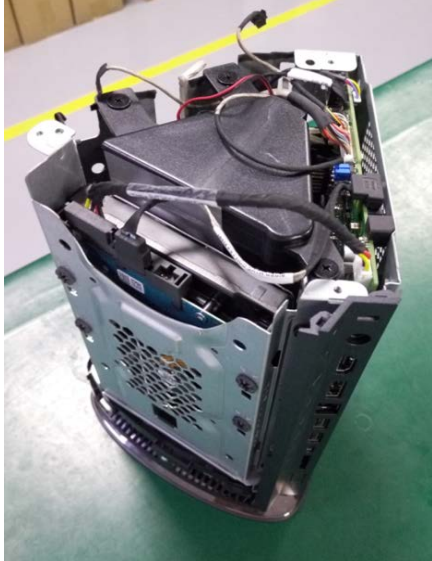



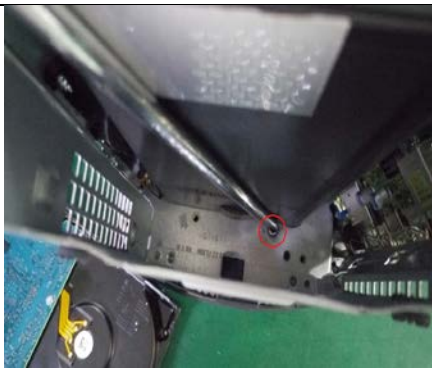
2. Remove 3pcs screws from bottom cover, remove bottom cover from chassis.



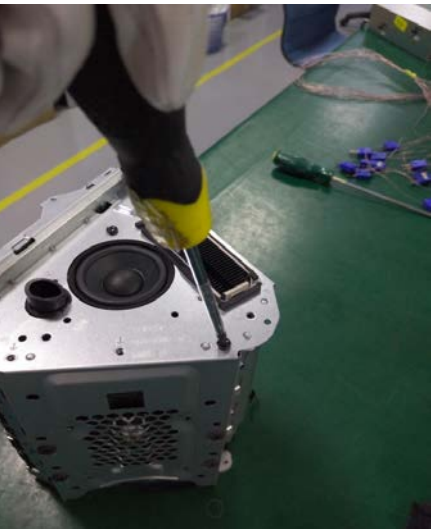
3. Remove Chassis outer covering.



4. Remove Rear I/O bezel.

		<p>5. Remove all cable from the unit.</p>
		<p>6. Remove HDD from the unit.</p>
		<p>7. Remove Screw that connect Chassis and top cover.</p>



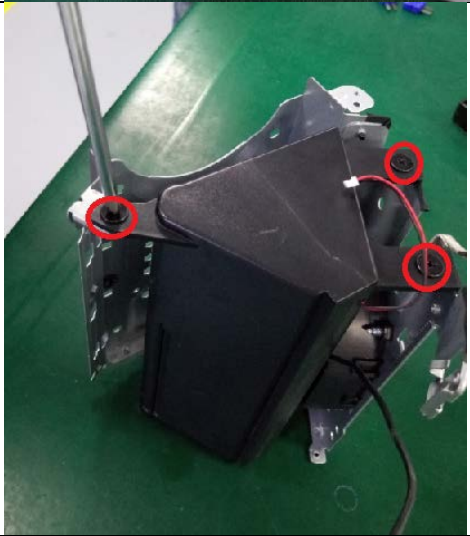
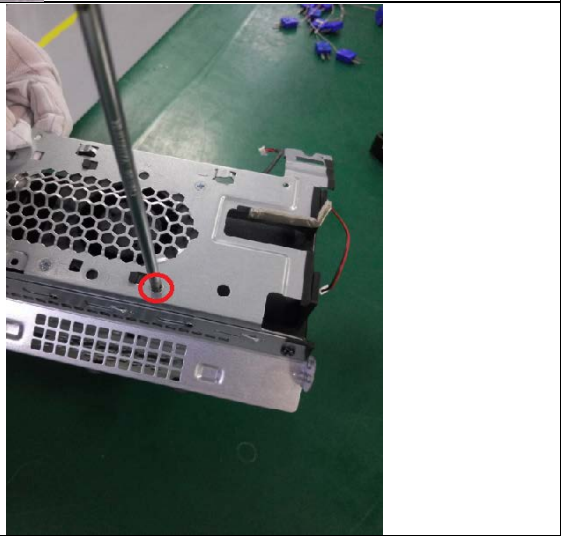




8. Remove top bezel and top cover from units.

9. Remove Memory cover.

	<p>10. Remove screws from chassis iron part.</p>
	<p>11. Separate chassis iron part.</p>
	<p>12. Remove Memory from Motherboard.</p>

		<p>13. Remove heat sink from Motherboard.</p>
		<p>14. Remove Motherboard from chassis Iron part.</p>
		<p>15. Remove system fan and speaker from chassis iron part.</p>
		<p>16. Open the power adapter by mechanical force and remove PCA and capacitor &gt; 25mm in size.</p>



